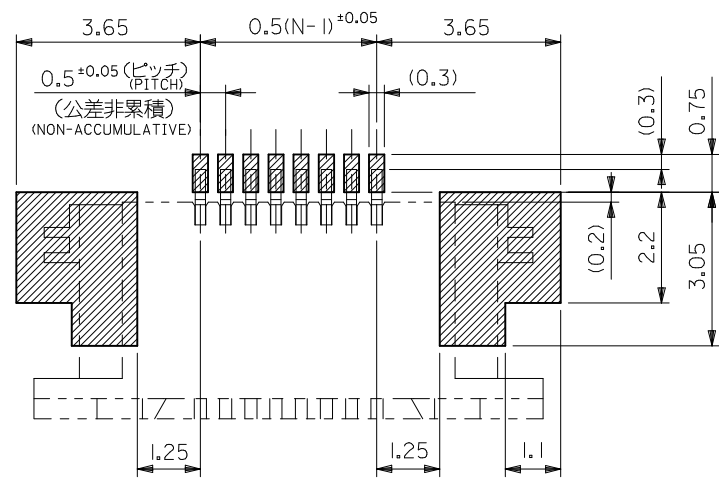


注記(NOTES)

1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX、下方向 0.15MAX、とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
4. 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

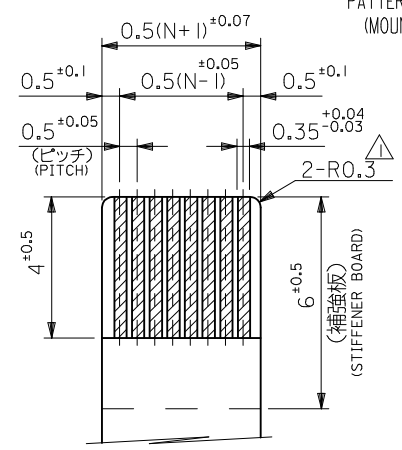
MODEL NO. 52689-***49

REVISED EC NO: J2016-1029 DRWN: SKITAZAWA 2016/03/30 CHKD: APPR: KUSUHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER	UNDER	± 0.03	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	0.25 OVER	0.5 UNDER	± 0.05	CHECKED BY K. TOJO	DATE '04/02/03				
	0.5 OVER	1.0 UNDER	± 0.1	APPROVED BY M. SASAO	DATE '04/02/03				
1.0 OVER	10 UNDER	± 0.2	MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-52689-034	SHEET NO. 1 OF 2			
10 OVER	30 UNDER	± 0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
30 OVER		± 0.3	SIZE A3						

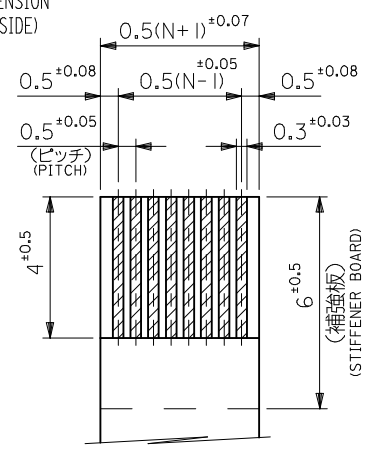


参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

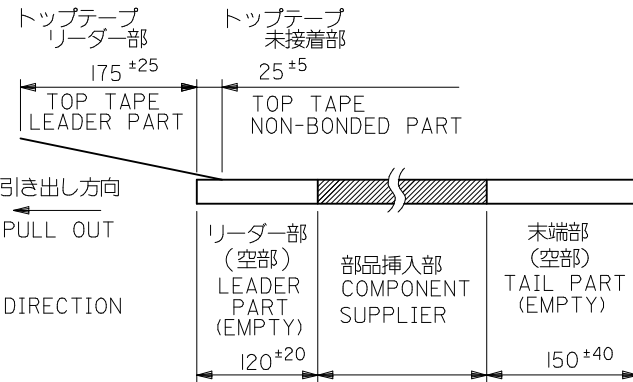
17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
MODEL NO.						ORDER No. オーダー番号		

REVISED EC NO: J2016-1029 DRWN: SKITAZAWA 2016/03/30 CHKD: APPR: TKSUJHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.03	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-		
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K. TOJO	DATE '04/02/03			
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/02/03			
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
10 OVER	30 UNDER	±0.25	SEE TABLE		SD-52689-034		2 OF 2	
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3			

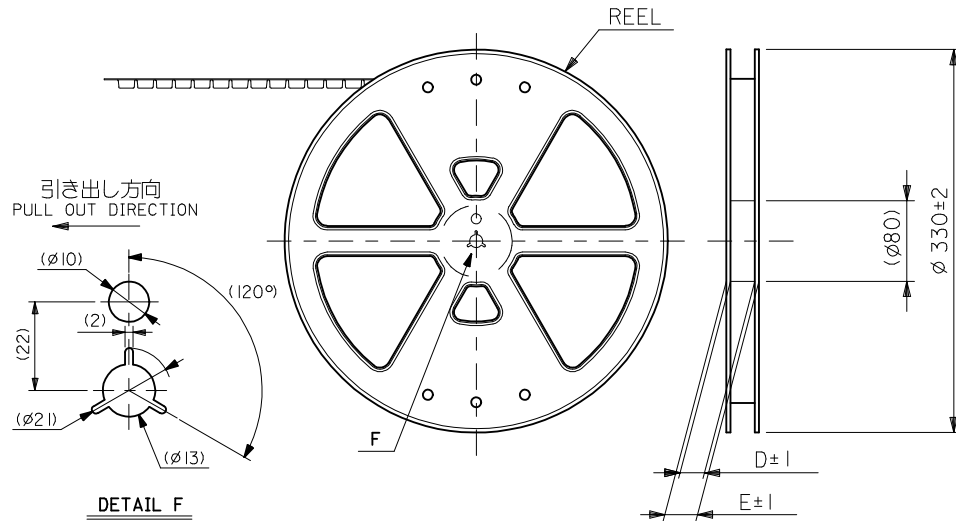
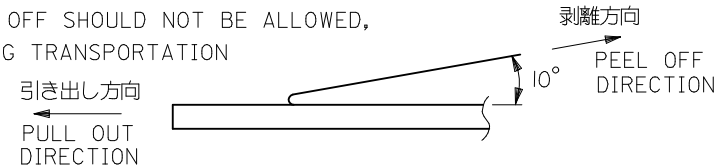
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

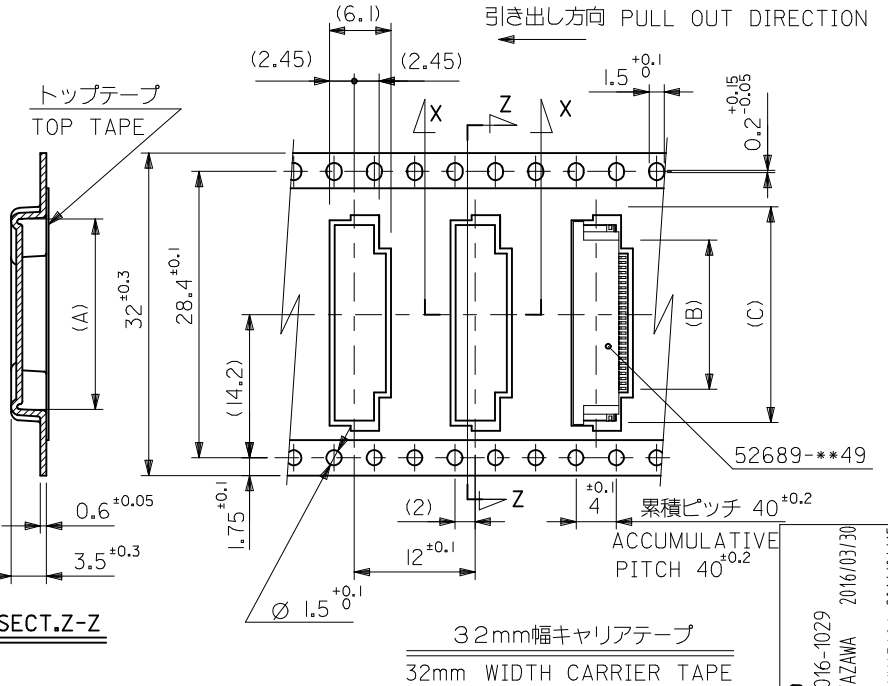
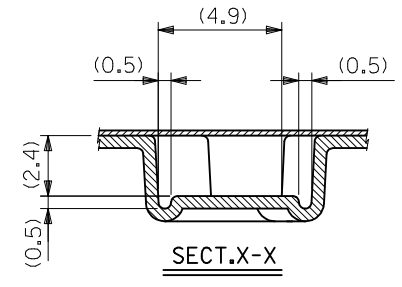
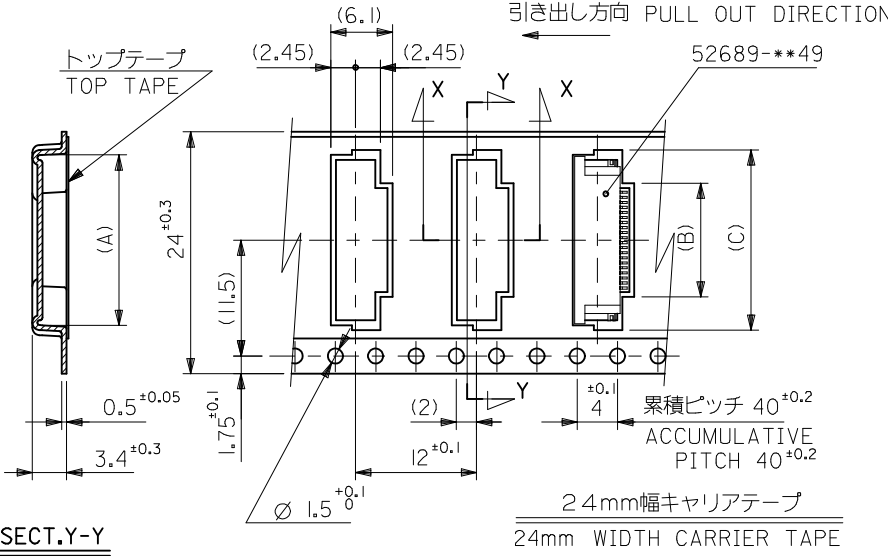
- 本製品は52689-***93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-***93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

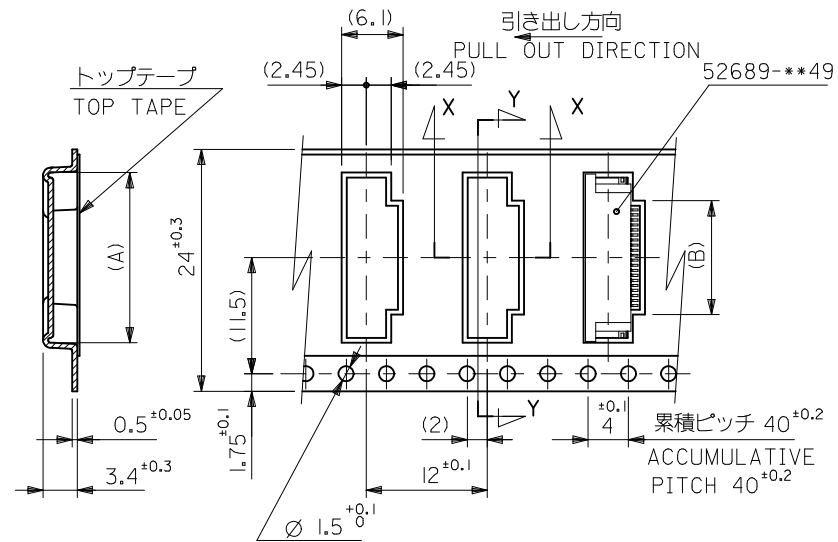
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO: J2016-1029 DRWN:SKITAZAWA 2016/03/30 CHKD: APPR:TKUJHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K.TOJO	DATE 2004/02/03		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M.SASAO	DATE 2004/02/03		
1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	SEE SHEET 2,3		SD-52689-035		1 OF 3
30 OVER		±0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	ANGULAR ±3		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



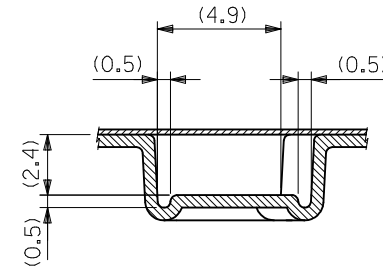
32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30
24	29.4	25.4	17.4	10.8	16.4	-2087	20
			16.4	9.8	15.4	-1887	18
			15.4	8.8	14.4	-1687	16
			14.9	8.3	13.9	-1587	15
			12.4	5.8	11.4	-1087	10
			11.4	4.8	10.4	-0887	8
			10.9	4.3	9.9	-0787	7
9.9	3.3	8.9	52689 -0587	5			

REVISED	EC NO: J2016-1029	DRWN:SKITAZAWA	2016/03/30	CHKD:	APPR:KUSUHARA01	2016/04/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	0.25 UNDER UNDER ±0.03	0.25 OVER 0.5 UNDER ±0.05	0.5 OVER 1.0 UNDER ±0.1	1.0 OVER 10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MODEL NO. 52689-**-87	CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	種数 CIRCUIT
DIMENSION STYLE										SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION		DRAWN BY		DATE		TITLE		0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-			
MM ONLY										---		METRIC		☉		H.KAWABATA		2004/02/03		MOLLEX		SD-52689-035		SHEET NO. 2 OF 3	
SEE TABLE										SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		M.SASAO		2004/02/03		DOCUMENT NO.							



SECT.Y-Y

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



SECT.X-X

52689-***87	24	29.4	25.4	11.8	17.4	52689-2287	22
MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2016-1029 DRWN:SKITAZAWA 2016/03/30 CHKD: APPR:KUSUHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex MATERIAL NO. DOCUMENT NO. SD-52689-035 SHEET NO. 3 OF 3		
	1.0 OVER	10 UNDER	±0.2	K.TOJO	2004/02/03			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SEE TABLE			
30 OVER		±0.3	M.SASAO	2004/02/03	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	ANGULAR	±3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					